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1/7/1 DIALOG(R)File 352:Derwent WPI (c) 2001 Derwent Info Ltd. All rts. reserv.

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 Unsaturated polyester resin composition - cured using organic peroxides made up of two parts having both ten hour half-lives at different

Patent Assignee: SEKISUI CHEM IND CO LTD (SEKI ) Number of Countries: 001 Number of Patents: 001

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JP 10036653 Α 7 CO8L-067/06

Abstract (Basic): JP 10036653 A

A 0.5-10 pts. wt. organic peroxide is added to the 100 pts. wt. -resin portion of an unsatd. polyester resin. The organic peroxide contains: (a) a first organic peroxide having a 10-hour half life temp. of 50 deg. C or more and less than 85 deg. C; and (b) a sec. organic peroxide having a 10-hour half life temp. of 85 deg. C or more and less than 110 deg. C with a wt. ratio of 1:9-9:1. Also claimed is that thermal compression moulding is applied to the unsatd. polyester resin compsn. Where, the temp. of a die site for forming the thick-wall section of a moulded part is higher than the temp. of the die site for forming the thin-wall section of the moulded part by 5-100 deg. C.

USE - The unsatd. polyester resin compsn. and the thermal

compression moulding yield the moulded part.

ADVANTAGE - The method prolongs the gelatinisation duration to evolve less pregel, and reduces the duration before completing hardening. The resulting moulded part has no poor surface, including the pregel. The method yields the moulded part having the thick-wall portion in a short compression period of time. Dwg. 0/3

Derwent Class: A23

International Patent Class (Main): CO8L-067/06

International Patent Class (Additional): B29C-043/02: B29C-043/52